

2026 是德科技 AI x 6G 元件測試論壇

Time	Topic
12:30	Check-in & Booth Demo
13:05	Opening & Welcome
13:10	Characterization of mmWave and Sub-THz Devices and Circuits for Emerging Applications
	Shang-Ming Yeh, Solutions Engineer, Keysight
13:35	Automated Multi-Port Testing and BER/FEC Validation for Reliable High-Speed Interconnects
	Jeff Lin/Jacky Yu, Solutions Engineer, Keysight
14:00	Empowering Scalable AI Architectures through High-Speed Network, CPO, and SiPh Validation
	Joe Lin, AI Solutions Manager, Keysight
14:25	Phased Array Antennas Enabling Next-Generation Radar and Satellite Communications
	Philip Chang, Solutions Architect, Keysight
14:50	Characterizing ReRAM and AI-Driven WBG Power Devices for Advanced AI Hardware
	Jay Liao, Solutions Engineer, Keysight
15:15	Tea Break & Booth Demo
15:40	Challenges of mmWave/Sub-THz Measurement on Component and OTA System
	Dau-Chyrh Chang, CTO of BoJiang & IEEE Life Fellow
16:05	AI Scale Up and Scale Out Networking with Samtec CPX Architecture CPC & CPO
	Ray Chien, Series Manger, Samtec
16:30	Broadband Single Sweep DC-250GHz Wafer Test Solution
	Dr. Choon Beng Sia, Technical Director of FormFactor & SSG Fellow
16:55	250 GHz Single-Sweep Wafer-Level Measurement and PIC Characterization for Next-Gen Communication Systems and AI
	Lori Pei, Technical Support Manager, MPI
17:20	Wrap-up & Lucky Draw